

Title (en)

USE OF A LAYER CONSISTING OF HYDROPHOBIC, LINEAR OR TWO-DIMENSIONAL POLYCYCLIC AROMATICS AS A BARRIER LAYER OR AN ENCAPSULATION AND ELECTRIC COMPONENTS CONSTRUCTED WITH A LAYER OF THIS TYPE AND COMPRISING ORGANIC POLYMERS

Title (de)

VERWENDUNG EINER SCHICHT AUS HYDROPHOBEN, LINEAR ODER ZWEIDIMENSIONAL POLYZYKLISCHEN AROMATEN ALS SPERRSCHICHT ODER KAPSELUNG UND MIT EINER DERARTIGEN SCHICHT AUFGEBAUTE ELEKTRISCHE BAUELEMENTE MIT ORGANISCHEN POLYMEREN

Title (fr)

UTILISATION D'UNE COUCHE FORMEE D'AROMATES HYDROPHOBES, POLYCYCLIQUES LINEAIRES OU BIDIMENSIONNELS, COMME COUCHE D'ARRET OU DE BLINDAGE, ET COMPOSANTS ELECTRIQUES DOTES D'UNE COUCHE DE CE TYPE ET DE POLYMERES ORGANIQUES

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Application

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Abstract (en)

[origin: WO2005015959A1] The invention relates to an electric component constructed with organic layers and comprising a layer consisting of a hydrophobic, linear or two-dimensional polycyclic aromatic with between 3 and 12 ring structures, including phthalocyanines containing metal or devoid of metal, which have -H and/or -F, alkyl groups, aryl groups and/or fluorinated hydrocarbons as residual groups, said layer being used as a barrier layer or an encapsulation. This permits in particular hybrid constructions consisting of SM layers and polymer layers to be obtained. In addition, a retroactive encapsulation of the component is no longer required.

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